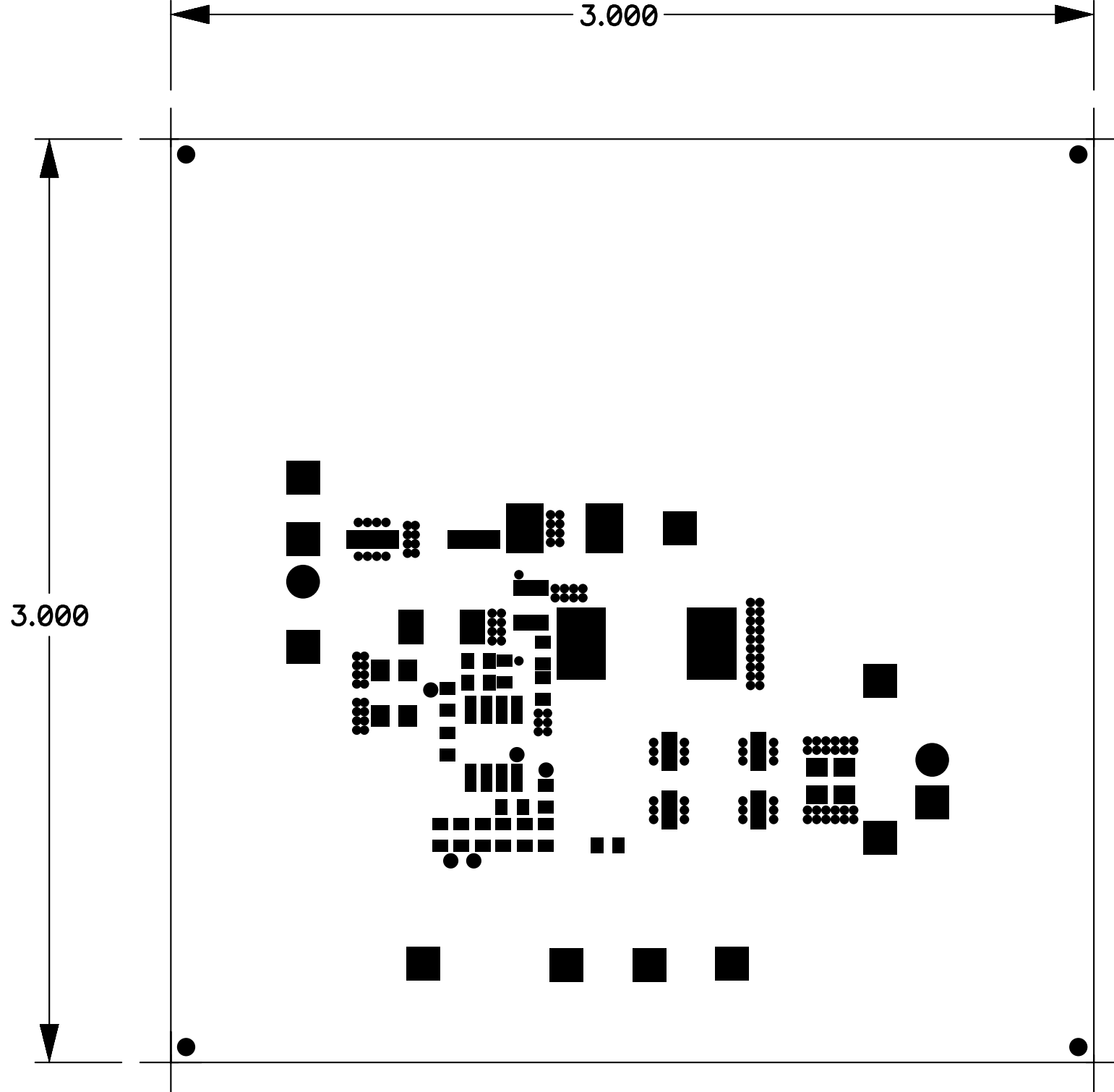


TEXAS INSTRUMENTS		Copper Layer Name		Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
		Top	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. HPA154	Rev. E1	L1										
Date: 3/20/06	Filename: HPA154E1.pcb	Engineer: Brant Johnson	PCB Dsgnr: Al Zollo	Modified Date: Mon Mar 27, 2006				Time Stamp: 15:23:36				

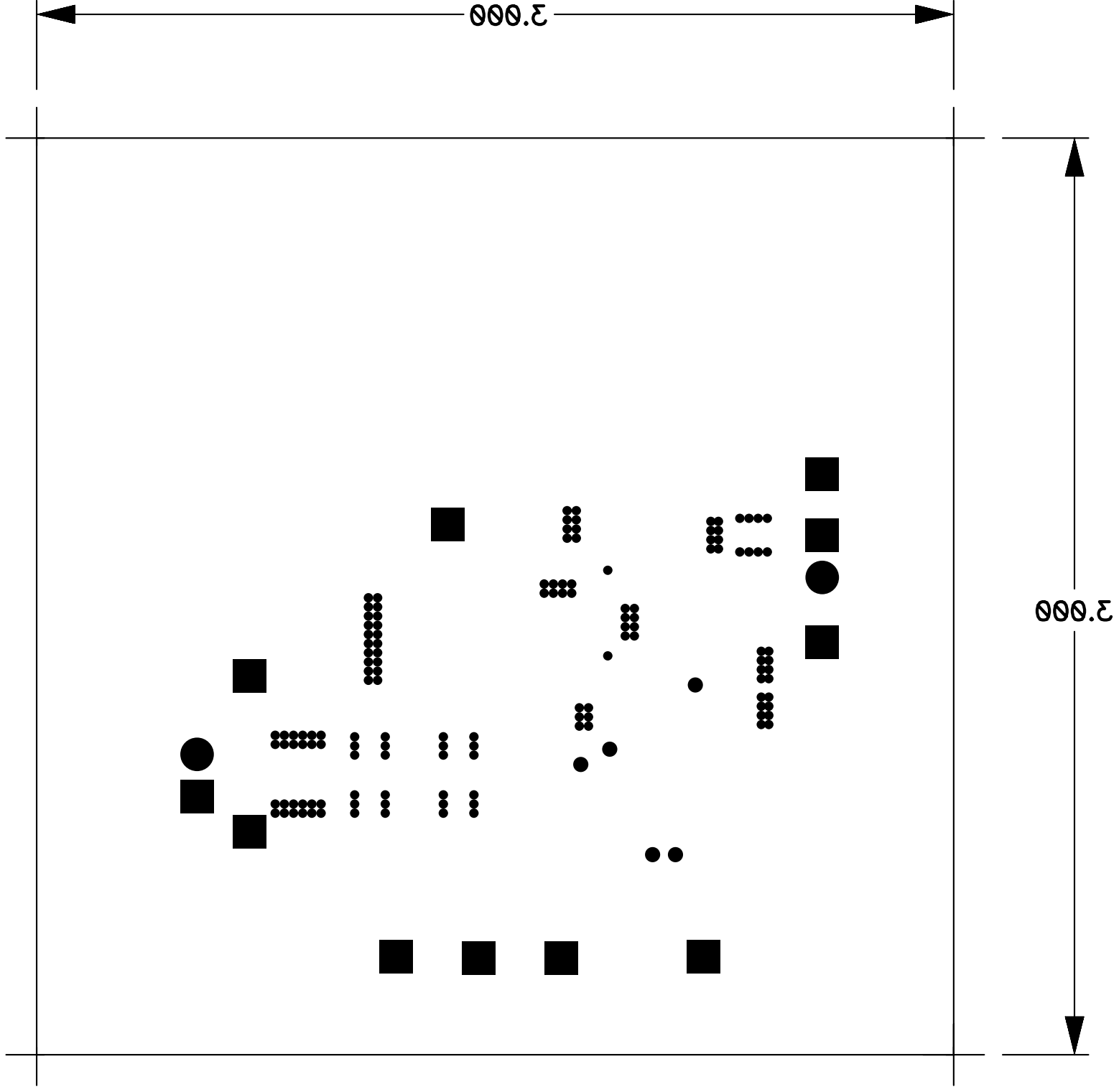
Date: 3/20/06		Filename: HP4124E1.pcb		Engineer: Brant Johnson		PCB Dsgnr: Al Zollo		Modified Date: Mon Mar 27, 2006				Time Stamp: 12:23:36	
Board No. HP4124		Rev. E1		Copper Layer Name		Silkscreen		2 Mask		P Mask		Assembly	
				Top		Top		Top		Top		Top	
		L2		Bot		Bot		Bot		Bot		Bot	
				Fab Drawing									

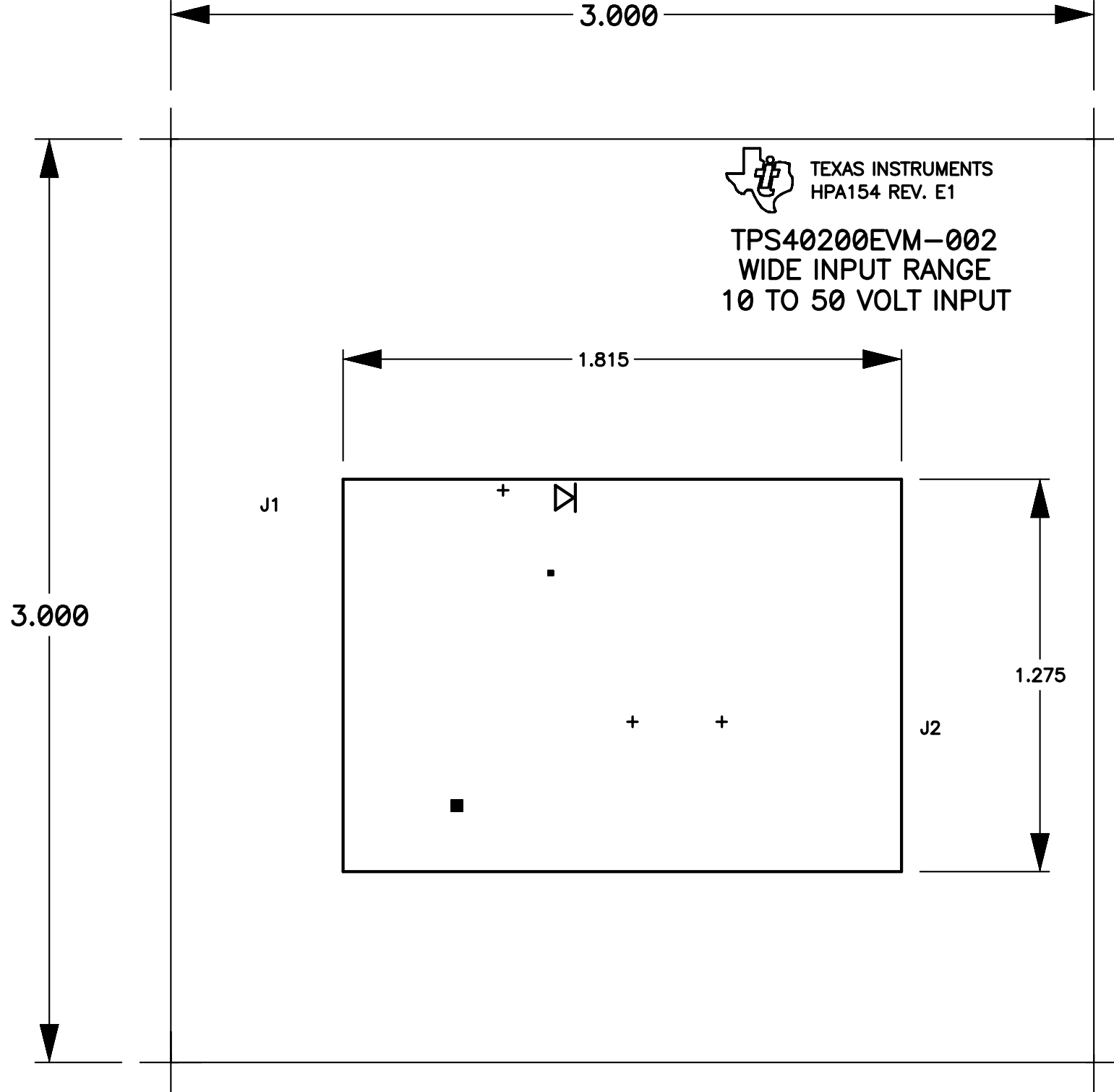




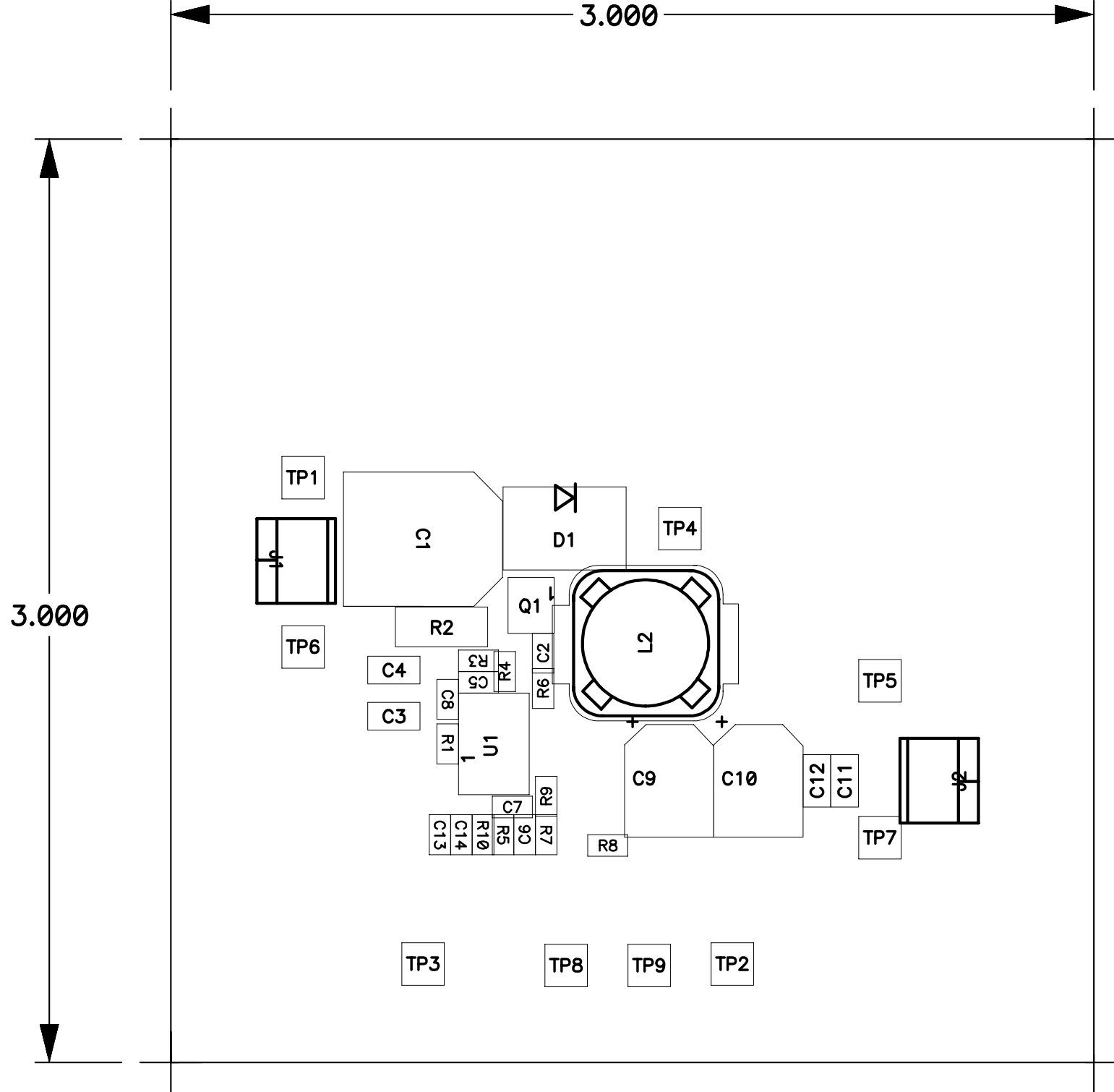
TEXAS INSTRUMENTS		Copper Layer Name		Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
		Top	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. HPA154	Rev. E1					M1						
Date: 3/20/06	Filename: HPA154E1.pcb	Engineer: Brant Johnson	PCB Dsgnr: Al Zollo	Modified Date: Mon Mar 27, 2006				Time Stamp: 15:23:36				

Date: 3/20/06		Filename: HPA124E1.pcb		Engineer: Brant Johnson		PCB Dsgnr: Al Zollo		Modified Date: Mon Mar 27, 2006				Time Stamp: 12:23:36							
Board No. HPA124		Rev. E1						Copper Layer Name		Silkscreen		2 Mask		P Mask		Assembly		Fab Drawing	
								Top		Top		Top		Top		Top		Bot	
								Bot		Bot		Bot		Bot		Bot		Bot	
										MS									





TEXAS INSTRUMENTS		Copper Layer Name		Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
		Top	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. HPA154	Rev. E1			S1								
Date: 3/20/06	Filename: HPA154E1.pcb	Engineer: Brant Johnson	PCB Dsgnr: Al Zollo	Modified Date: Mon Mar 27, 2006				Time Stamp: 15:23:36				



TEXAS INSTRUMENTS		Copper Layer Name		Silkscreen		S Mask		P Mask		Assembly		Fab Drawing
		Top	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No.	HPA154	Rev.	E1							TA		
Date:	3/20/06	Filename:	HPA154E1.pcb	Engineer:	Brant Johnson	PCB Dsgnr:	Al Zollo	Modified Date:	Mon Mar 27, 2006		Time Stamp:	15:23:36

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